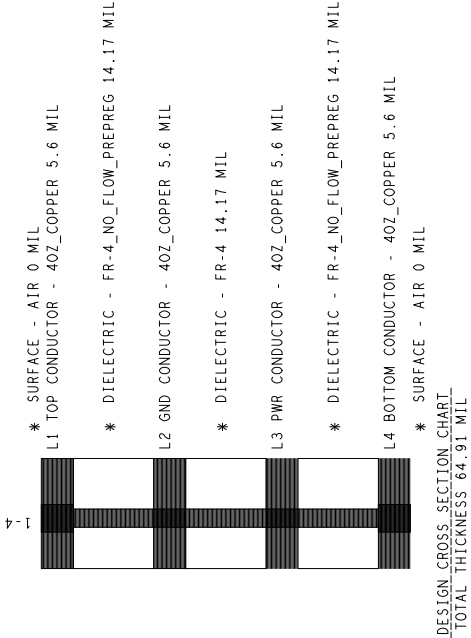


DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILS			
FIGURE	FINISHED_SIZE	PLATED	QTY
A	11.81	PLATED	710
B	51.0	PLATED	4
C	157.48	PLATED	7
D	125.98	NON-PLATED	4

TOTAL HOLES: 725

Finished Hole Tolerance - All units are in Inches -		
Finish Hole Diameter	Plated Through Finish Hole Diameter	Non Plated Through Finish Hole Diameter
0.008"-0.013"	+0.002/-FHS"	+/-0.002"
0.014"-0.063"	+/-0.003"	+/-0.002"
0.064"-0.156"	+/-0.004"	+/-0.003"
0.157"-0.250"	+/-0.007"	+/-0.004"
0.251" and up	Non Plated Only	+/-0.005"
0.125"		+0.003/-0.000"



REVISION DATE



APMS Group AGRATE B. ITALY

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Drawn RIGO M. date 28-June-2024
Approved date

Description

DRILLING AND PROFILING

Symbol

STSPIN32G4

Group

SERVO_INV1

TOLERANCE UNLESS NOTED
UNIT=MM

Linear 0 >10 >50 >200
<10 <50 <200 >200

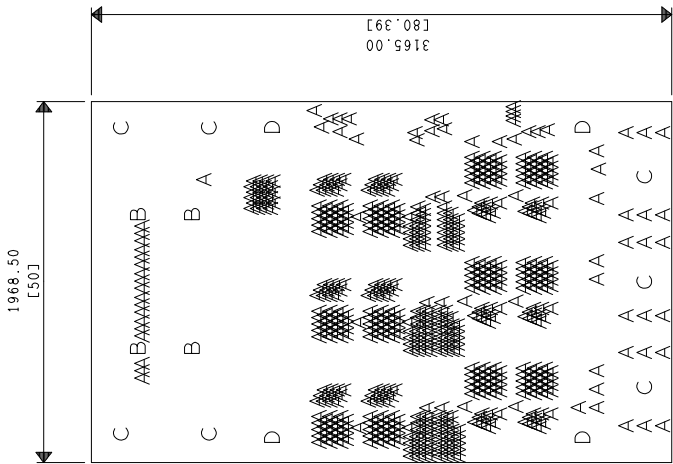
midle ±0.1 ±0.2 ±0.3 ±0.5 ±1°

accurate ±0.05 ±0.1 ±0.15 ±0.25 ±30°

Material

ANG. LES.

Treatment and surface finishing



FABRICATION NOTES :

- 1:FABRICATE USING LATEST REVISION OF STM SPECIFICATION.
- 2:FABRICATE USING MASTER ARTWORK SERVO INV1 R1 FOR CIRCUIT PATTERN.
NO DEVIATION FROM MASTER ARTWORK ARE PERMITTED WITHOUT WRITTEN APPROVAL FROM AN AUTHORIZED "CLIENT NAME" REPRESENTATIVE.
- 3-VENDOR MUST BE UL QUALIFIED AND BOARDS MUST BE IDENTIFIED WITH APPROPRIATE VENDOR UL IDENTIFICATION MARK, LOT OR JOB NUMBER AND PCB MATERIAL FLAMMABILITY RATING (94V-0) MINIMUM.
- 4:MATERIAL - FR4 RoHS COMPLIANT MINIMUM 170 C (High Tg)
SEE "Cross Section Chart" FOR BOARD THICKNESS, COPPER WEIGHT AND LAYER CONSTRUCTION.
- 5:BLUE SOLDER MASK BOTH SIDE OF BOARD WITH LIQUID PHOTO IMAGEABLE SOLDERMASK.
- 6:FINISH - HAL LF RoHS compliant
- 7:FOR SMT COMPONENTS WITH PIN PITCH OF 0.019 INCH OR MORE NO GANG RELIEF OF SOLDER MASK IS ALLOWED.
- 8:SILKSCREEN TO BE WHITE, NON CONDUCTIVE, EPOXY INK OR EQUIVALENT.
- 9:THIS IS NOT A CONTROLLED IMPEDANCE BOARD.
- 10:DESIGNATED AREA OR INSPECTION AND TEST STAMP.
- 11:ON SMB PCB MUST BE IDENTIFIED MANUFACTURER LOGO AND PCB TYPE (MEANS OF MATERIAL TYPE INDICATED ON THE YELLOW CARD DOCUMENT).
- 12:TEARDROPPING OF VIAS AND PADS ALLOWED AT PAD TO TRACE INTERSECTION TO INSURE A 2 MILS ANULAR RING AT THE JUNCTION.
- 13:REMOVE SILKSCREEN FROM SOLDERABLE SURFACES.
- 14:ALL BOARD TO BE 100% ELECTRICALLY NETLIST TESTED FOR OPENS AND ON SHORTS.APPLY TEST STAMP IN REFERENCED AREA.
- 15:THIS BOARD SHALL BE FULLY COMPLIANT WITH UL796.